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Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are Embedded - System On Chip (SoC)?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions, SoCs combine a central

Details

Product Status	Active
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A53 MPCore™ with CoreSight™, Dual ARM®Cortex™-R5 with CoreSight™
Flash Size	-
RAM Size	256KB
Peripherals	DMA, WDT
Connectivity	CANbus, EBI/EMI, Ethernet, I ² C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	500MHz, 1.2GHz
Primary Attributes	Zynq®UltraScale+™ FPGA, 154K+ Logic Cells
Operating Temperature	0°C ~ 100°C (TJ)
Package / Case	625-BFBGA, FCBGA
Supplier Device Package	625-FCBGA (21x21)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xczu3cg-1sfva625e

Table 1: Absolute Maximum Ratings⁽¹⁾ (Cont'd)

Symbol	Description	Min	Max	Units
Video Codec Unit				
V _{CCINT_VCU}	Internal supply voltage for the video codec unit.	-0.500	1.000	V
PL System Monitor				
V _{CCADC}	PL System Monitor supply relative to GNDADC.	0.500	2.000	V
V _{REFP}	PL System Monitor reference input relative to GNDADC.	0.500	2.000	V
Temperature				
T _{STG}	Storage temperature (ambient).	-65	150	°C
T _{SOL}	Maximum soldering temperature. ⁽¹²⁾	-	260	°C
T _j	Maximum junction temperature. ⁽¹²⁾	-	125	°C

Notes:

1. Stresses beyond those listed under Absolute Maximum Ratings might cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time might affect device reliability.
2. When operating outside of the recommended operating conditions, refer to [Table 6](#), [Table 7](#), and [Table 8](#) for maximum overshoot and undershoot specifications.
3. V_{CCINT_IO} must be connected to V_{CCBRAM}.
4. V_{CCAUX_IO} must be connected to V_{CCAUX}.
5. The lower absolute voltage specification always applies.
6. If V_{CCO} is 3.3V, the maximum voltage is 3.4V.
7. For I/O operation, see the *UltraScale Architecture SelectIO Resources User Guide* ([UG571](#)).
8. AC coupled operation is not supported for RX termination = floating.
9. For GTY transceivers, DC coupled operation is not supported for RX termination = GND.
10. DC coupled operation is not supported for RX termination = programmable.
11. For more information on supported GTH or GTY transceiver terminations see the *UltraScale Architecture GTH Transceiver User Guide* ([UG576](#)) or *UltraScale Architecture GTY Transceiver User Guide* ([UG578](#)).
12. For soldering guidelines and thermal considerations, see the *Zynq UltraScale+ MPSoC Packaging and Pinout Specifications* ([UG1075](#)).

Table 11: Power Supply Ramp Time (Cont'd)

Symbol	Description	Min	Max	Units
$T_{V_{CCO_PSDDR}}$	Ramp time from GND to 95% of V_{CCO_PSDDR} .	0.2	40	ms
$T_{V_{CC_PSDDR_PLL}}$	Ramp time from GND to 95% of $V_{CC_PSDDR_PLL}$.	0.2	40	ms
$T_{V_{CCO_PSIO}}$	Ramp time from GND to 95% of V_{CCO_PSIO} .	0.2	40	ms

DC Input and Output Levels

Values for V_{IL} and V_{IH} are recommended input voltages. Values for I_{OL} and I_{OH} are guaranteed over the recommended operating conditions at the V_{OL} and V_{OH} test points. Only selected standards are tested. These are chosen to ensure that all standards meet their specifications. The selected standards are tested at a minimum V_{CCO} with the respective V_{OL} and V_{OH} voltage levels shown. Other standards are sample tested.

PS I/O Levels

Table 12: PS MIO and CONFIG DC Input and Output Levels⁽¹⁾

I/O Standard	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
LVC MOS33	-0.300	0.800	2.000	V_{CCO_PSIO}	0.40	2.40	12	-12
LVC MOS25	-0.300	0.700	1.700	$V_{CCO_PSIO} + 0.30$	0.70	1.70	12	-12
LVC MOS18	-0.300	35% V_{CCO_PSIO}	65% V_{CCO_PSIO}	$V_{CCO_PSIO} + 0.30$	0.45	$V_{CCO_PSIO} - 0.45$	12	-12

Notes:

1. Tested according to relevant specifications.

Table 13: PS DDR DC Input and Output Levels⁽¹⁾

DDR Standard	V_{IL}		V_{IH}		V_{OL} ⁽²⁾	V_{OH} ⁽²⁾	I_{OL}	I_{OH}
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
DDR4	0.000	$V_{REF} - 0.100$	$V_{REF} + 0.100$	V_{CCO_PSDDR}	$0.8 \times V_{CCO_PSDDR} - 0.150$	$0.8 \times V_{CCO_PSDDR} + 0.150$	10	-0.1
LPDDR4	0.000	$V_{REF} - 0.100$	$V_{REF} + 0.100$	V_{CCO_PSDDR}	$0.3 \times V_{CCO_PSDDR} - 0.150$	$0.3 \times V_{CCO_PSDDR} + 0.150$	0.1	-10
DDR3	-0.300	$V_{REF} - 0.100$	$V_{REF} + 0.100$	V_{CCO_PSDDR}	$0.5 \times V_{CCO_PSDDR} - 0.175$	$0.5 \times V_{CCO_PSDDR} + 0.175$	8	-8
LPDDR3	0.000	$V_{REF} - 0.100$	$V_{REF} + 0.100$	V_{CCO_PSDDR}	$0.5 \times V_{CCO_PSDDR} - 0.150$	$0.5 \times V_{CCO_PSDDR} + 0.150$	8	-8
DDR3L	-0.300	$V_{REF} - 0.090$	$V_{REF} + 0.090$	V_{CCO_PSDDR}	$0.5 \times V_{CCO_PSDDR} - 0.150$	$0.5 \times V_{CCO_PSDDR} + 0.150$	8	-8

Notes:

1. Tested according to relevant specifications.
2. DDR4 V_{OL}/V_{OH} specifications are only applicable for DQ/DQS pins.

AC Switching Characteristics

All values represented in this data sheet are based on the speed specifications in the Vivado® Design Suite as outlined in [Table 25](#).

Table 25: Speed Specification Version By Device

2017.1	Device
1.08	XCZU4CG, XCZU4EG, XCZU4EV, XCZU5CG, XCZU5EG, XCZU5EV, XCZU11EG
1.10	XCZU2CG, XCZU2EG, XCZU3CG, XCZU3EG, XCZU6CG, XCZU6EG, XCZU7CG, XCZU7EG, XCZU7EV, XCZU9CG, XCZU9EG, XCZU15EG, XCZU17EG, XCZU19EG

Switching characteristics are specified on a per-speed-grade basis and can be designated as Advance, Preliminary, or Production. Each designation is defined as follows:

Advance Product Specification

These specifications are based on simulations only and are typically available soon after device design specifications are frozen. Although speed grades with this designation are considered relatively stable and conservative, some under-reporting might still occur.

Preliminary Product Specification

These specifications are based on complete ES (engineering sample) silicon characterization. Devices and speed grades with this designation are intended to give a better indication of the expected performance of production silicon. The probability of under-reporting delays is greatly reduced as compared to Advance data.

Product Specification

These specifications are released once enough production silicon of a particular device family member has been characterized to provide full correlation between specifications and devices over numerous production lots. There is no under-reporting of delays, and customers receive formal notification of any subsequent changes. Typically, the slowest speed grades transition to production before faster speed grades.

Testing of AC Switching Characteristics

Internal timing parameters are derived from measuring internal test patterns. All AC switching characteristics are representative of worst-case supply voltage and junction temperature conditions.

For more specific, more precise, and worst-case guaranteed data, use the values reported by the static timing analyzer and back-annotate to the simulation net list. Unless otherwise noted, values apply to all Zynq UltraScale+ MPSoC.

PS Configuration

Table 39: Processor Configuration Access Port Switching Characteristics

Symbol	Description	Speed Grade and V_{CCINT} Operating Voltages					Units
		0.90V	0.85V		0.72V		
		-3	-2	-1	-2	-1	
F_{PCAPCK}	Maximum processor configuration access port (PCAP) frequency.	200	200	200	150	150	MHz

Table 40: Boundary-Scan Port Switching Characteristics

Symbol	Description	Speed Grade and V_{CCINT} Operating Voltages					Units
		0.90V	0.85V		0.72V		
		-3	-2	-1	-2	-1	
F_{TCK}	JTAG clock maximum frequency.	25	25	25	15	15	MHz
T_{TAPTCK}/T_{TCKTAP}	TMS and TDI setup and hold.	4.0/2.0	4.0/2.0	4.0/2.0	5.0/2.0	5.0/2.0	ns, Min
T_{TCKTDO}	TCK falling edge to TDO output.	16.1	16.1	16.1	24	24	ns, Max

Notes:

- The test conditions are configured to the LVCMOS 3.3V I/O standard with a 12 mA drive strength.

PS-GTR Transceiver

Table 56: PS-GTR Transceiver DC Specifications

Symbol	DC Parameter	Conditions	Min	Typ	Max	Units
DV _{PPIN}	Differential peak-to-peak input voltage (external AC coupled).		100	–	1200	mV
V _{IN}	Single-ended input voltage. Voltage measured at the pin referenced to GND.		75	–	V _{PS_MGTRAVCC}	mV
V _{CMIN}	Common mode input voltage.		–	0	–	mV
DV _{PPOUT}	Differential peak-to-peak output voltage. ⁽¹⁾	Transmitter output swing is set to maximum value.	800	–	–	mV
V _{CMOUTAC}	Common mode output voltage: AC coupled (equation based).		$V_{PS_MGTRAVCC} - D_{VPPOUT}/2$			mV
R _{IN}	Differential input resistance.		–	100	–	Ω
R _{OUT}	Differential output resistance.		–	100	–	Ω
R _{MGTRREF}	Resistor value between calibration resistor pin to GND.		497.5	500	502.5	Ω
T _{OSKEW}	Transmitter output pair (TXP and TXN) intra-pair skew (All packages).		–	–	20	ps
C _{EXT}	Recommended external AC coupling capacitor. ⁽²⁾		–	100	–	nF

Notes:

1. The output swing and pre-emphasis levels are programmable using the attributes discussed in the *Zynq UltraScale+ MPSoC Technical Reference Manual (UG1085)*, and can result in values lower than reported in this table.
2. Other values can be used as appropriate to conform to specific protocols and standards.

Table 57: PS-GTR Transceiver Clock DC Input Level Specification

Symbol	DC Parameter	Min	Typ	Max	Units
V _{IDIFF}	Differential peak-to-peak input voltage.	250	–	2000	mV
R _{IN}	Differential input resistance.	–	100	–	Ω
C _{EXT}	Required external AC coupling capacitor.	–	10	–	nF

Table 58: PS-GTR Transceiver Performance

Symbol	Description	Speed Grade			Units
		-3	-2	-1	
F _{GTRMAX}	PS-GTR maximum line rate.	6.0	6.0	6.0	Gb/s
F _{GTRMIN}	PS-GTR minimum line rate.	1.25	1.25	1.25	Gb/s

Table 59: PS-GTR Transceiver PLL/Lock Time Adaptation

Symbol	Description	Min	Typ	Max	Units
T _{LOCK}	Initial PLL lock.	–	–	0.11	ms
T _{DLOCK}	Clock recovery phase acquisition and adaptation time.	–	–	24 x 10 ⁶	UI

Table 67: USB 3.0 Protocol Characteristics (PS-GTR Transceivers)

Standard	Description	Line Rate (Mb/s)	Min	Max	Units
USB 3.0 Transmitter Jitter Generation					
USB 3.0	Total transmitter jitter.	5000	–	0.66	UI
USB 3.0 Receiver High Frequency Jitter Tolerance					
USB 3.0	Total receiver jitter tolerance.	5000	0.2	–	UI

Table 68: Serial-GMII Protocol Characteristics (PS-GTR Transceivers)

Standard	Description	Line Rate (Mb/s)	Min	Max	Units
Serial-GMII Transmitter Jitter Generation					
SGMII	Deterministic transmitter jitter.	1250	–	0.25	UI
Serial-GMII Receiver High Frequency Jitter Tolerance					
SGMII	Total receiver jitter tolerance.	1250	0.25	–	UI

PS System Monitor Specifications

Table 69: PS SYSMON Specifications

Parameter	Comments	Conditions	Min	Typ	Max	Units
$V_{CC_PSADC} = 1.8V \pm 3\%$, $T_j = -40^\circ C$ to $100^\circ C$, typical values at $T_j = 40^\circ C$						
ADC Accuracy ($T_j = -55^\circ C$ to $125^\circ C$) ⁽¹⁾						
Resolution			10	–	–	Bits
Sample rate			–	–	1	MS/s
RMS code noise	On-chip reference		–	1	–	LSBs
On-Chip Sensor Accuracy						
Temperature sensor error		$T_j = -55^\circ C$ to $110^\circ C$	–	–	± 3.5	$^\circ C$
		$T_j = 110^\circ C$ to $125^\circ C$	–	–	± 5	$^\circ C$
Supply sensor error ⁽²⁾	Supply voltages less than or electrically connected to V_{CC_PSADC} .	$T_j = -40^\circ C$ to $125^\circ C$	–	–	± 1	%
	Supply voltages nominally at 1.8V but with the potential to go above V_{CC_PSADC} .	$T_j = -40^\circ C$ to $125^\circ C$	–	–	± 1.5	%
	Supply voltages nominally in the 2.0V to 3.3V range.	$T_j = -40^\circ C$ to $125^\circ C$	–	–	± 2.5	%

Notes:

- ADC offset errors are removed by enabling the ADC automatic offset calibration feature. The values are specified for when this feature is enabled.
- Supply sensor offset and gain errors are removed by enabling the automatic offset and gain calibration feature. The values are specified for when this feature is enabled.

Table 74: Maximum Physical Interface (PHY) Rate for Memory Interfaces (Cont'd)

Memory Standard	Package ⁽¹⁾	DRAM Type	Speed Grade and V _{CCINT} Operating Voltages					Units
			0.90V	0.85V		0.72V		
			-3	-2	-1	-2	-1	
DDR3L	All FFV packages and FBVB900	Single rank component	1866	1866	1866	1866	1600	Mb/s
		1 rank DIMM ⁽²⁾⁽³⁾	1600	1600	1600	1600	1333	Mb/s
		2 rank DIMM ⁽²⁾⁽⁵⁾	1333	1333	1333	1333	1066	Mb/s
		4 rank DIMM ⁽²⁾⁽⁶⁾	800	800	800	800	606	Mb/s
	SFVC784	Single rank component	1600	1600	1600	1600	1600	Mb/s
		1 rank DIMM ⁽²⁾⁽³⁾	1600	1600	1600	1600	1333	Mb/s
		2 rank DIMM ⁽²⁾⁽⁵⁾	1333	1333	1333	1333	1066	Mb/s
		4 rank DIMM ⁽²⁾⁽⁶⁾	800	800	800	800	606	Mb/s
QDR II+	All	Single rank component ⁽⁷⁾	633	633	600	600	550	MHz
RLDRAM 3	All FFV packages and FBVB900	Single rank component	1200	1200	1066	1066	933	MHz
	SFVC784	Single rank component	1066	1066	933	933	800	MHz
QDR IV XP	All	Single rank component	1066	1066	1066	933	933	MHz
LPDDR3	All	Single rank component	1600	1600	1600	1600	1600	Mb/s

Notes:

1. The SBVA484 and SFVA625 packages do not support the PL memory interfaces.
2. Dual in-line memory module (DIMM) includes RDIMM, SODIMM, UDIMM, and LRDIMM.
3. Includes: 1 rank 1 slot, DDP 2 rank, LRDIMM 2 or 4 rank 1 slot.
4. For the DDR4 DDP components at -3 and -2 speed grades and V_{CCINT} = 0.85V, the maximum data rate is 2133 Mb/s for six or more DDP devices. For five or less DDP devices, use the single rank DIMM data rates for the -3 and -2 speed grades at 0.85V.
5. Includes: 2 rank 1 slot, 1 rank 2 slot, LRDIMM 2 rank 2 slot.
6. Includes: 2 rank 2 slot, 4 rank 1 slot.
7. The QDRII+ performance specifications are for burst-length 4 (BL = 4) implementations.

Table 75: IOB High Density (HD) Switching Characteristics (Cont'd)

I/O Standards	T _{INBUF_DELAY_PAD_I}					T _{OUTBUF_DELAY_O_PAD}					T _{OUTBUF_DELAY_TD_PAD}					Units
	0.90V		0.85V		0.72V	0.90V		0.85V		0.72V	0.90V		0.85V		0.72V	
	-3	-2	-1	-2	-1	-3	-2	-1	-2	-1	-3	-2	-1	-2	-1	
HSTL_I_F	0.856	0.856	0.900	0.856	0.900	1.611	1.611	1.762	1.611	1.762	1.313	1.313	1.417	1.313	1.417	ns
HSTL_I_S	0.856	0.856	0.900	0.856	0.900	1.798	1.798	1.913	1.798	1.913	1.630	1.630	1.780	1.630	1.780	ns
HSUL_12_F	0.780	0.780	0.867	0.780	0.867	1.573	1.573	1.703	1.573	1.703	1.222	1.222	1.335	1.222	1.335	ns
HSUL_12_S	0.780	0.780	0.867	0.780	0.867	1.711	1.711	1.864	1.711	1.864	1.536	1.536	1.665	1.536	1.665	ns
LVC MOS12_F_12	0.918	0.918	0.976	0.918	0.976	1.689	1.689	1.856	1.689	1.856	1.202	1.202	1.317	1.202	1.317	ns
LVC MOS12_F_4	0.918	0.918	0.976	0.918	0.976	1.742	1.742	1.922	1.742	1.922	1.353	1.353	1.478	1.353	1.478	ns
LVC MOS12_F_8	0.918	0.918	0.976	0.918	0.976	1.714	1.714	1.879	1.714	1.879	1.292	1.292	1.432	1.292	1.432	ns
LVC MOS12_S_12	0.918	0.918	0.976	0.918	0.976	2.073	2.073	2.247	2.073	2.247	1.581	1.581	1.717	1.581	1.717	ns
LVC MOS12_S_4	0.918	0.918	0.976	0.918	0.976	1.979	1.979	2.182	1.979	2.182	1.633	1.633	1.772	1.633	1.772	ns
LVC MOS12_S_8	0.918	0.918	0.976	0.918	0.976	2.205	2.205	2.406	2.205	2.406	1.767	1.767	1.928	1.767	1.928	ns
LVC MOS15_F_12	0.905	0.905	0.958	0.905	0.958	1.713	1.713	1.892	1.713	1.892	1.275	1.275	1.428	1.275	1.428	ns
LVC MOS15_F_16	0.905	0.905	0.958	0.905	0.958	1.722	1.722	1.881	1.722	1.881	1.260	1.260	1.407	1.260	1.407	ns
LVC MOS15_F_4	0.905	0.905	0.958	0.905	0.958	1.825	1.825	1.959	1.825	1.959	1.453	1.453	1.557	1.453	1.557	ns
LVC MOS15_F_8	0.905	0.905	0.958	0.905	0.958	1.778	1.778	1.930	1.778	1.930	1.378	1.378	1.458	1.378	1.458	ns
LVC MOS15_S_12	0.905	0.905	0.958	0.905	0.958	1.991	1.991	2.139	1.991	2.139	1.516	1.516	1.648	1.516	1.648	ns
LVC MOS15_S_16	0.905	0.905	0.958	0.905	0.958	2.172	2.172	2.389	2.172	2.389	1.707	1.707	1.888	1.707	1.888	ns
LVC MOS15_S_4	0.905	0.905	0.958	0.905	0.958	2.313	2.313	2.483	2.313	2.483	1.952	1.952	2.123	1.952	2.123	ns
LVC MOS15_S_8	0.905	0.905	0.958	0.905	0.958	2.170	2.170	2.400	2.170	2.400	1.817	1.817	1.984	1.817	1.984	ns
LVC MOS18_F_12	0.915	0.915	0.958	0.915	0.958	1.805	1.805	1.962	1.805	1.962	1.383	1.383	1.471	1.383	1.471	ns
LVC MOS18_F_16	0.915	0.915	0.958	0.915	0.958	1.785	1.785	1.917	1.785	1.917	1.338	1.338	1.446	1.338	1.446	ns
LVC MOS18_F_4	0.915	0.915	0.958	0.915	0.958	1.868	1.868	2.013	1.868	2.013	1.472	1.472	1.599	1.472	1.599	ns
LVC MOS18_F_8	0.915	0.915	0.958	0.915	0.958	1.797	1.797	1.979	1.797	1.979	1.384	1.384	1.487	1.384	1.487	ns
LVC MOS18_S_12	0.915	0.915	0.958	0.915	0.958	2.201	2.201	2.408	2.201	2.408	1.762	1.762	1.894	1.762	1.894	ns
LVC MOS18_S_16	0.915	0.915	0.958	0.915	0.958	2.173	2.173	2.362	2.173	2.362	1.702	1.702	1.834	1.702	1.834	ns
LVC MOS18_S_4	0.915	0.915	0.958	0.915	0.958	2.346	2.346	2.567	2.346	2.567	1.951	1.951	2.092	1.951	2.092	ns
LVC MOS18_S_8	0.915	0.915	0.958	0.915	0.958	2.292	2.292	2.511	2.292	2.511	1.848	1.848	2.008	1.848	2.008	ns
LVC MOS25_F_12	0.988	0.988	1.042	0.988	1.042	2.153	2.153	2.453	2.153	2.453	1.692	1.692	1.856	1.692	1.856	ns
LVC MOS25_F_16	0.988	0.988	1.042	0.988	1.042	2.105	2.105	2.406	2.105	2.406	1.623	1.623	1.786	1.623	1.786	ns
LVC MOS25_F_4	0.988	0.988	1.042	0.988	1.042	2.344	2.344	2.554	2.344	2.554	1.842	1.842	2.039	1.842	2.039	ns
LVC MOS25_F_8	0.988	0.988	1.042	0.988	1.042	2.184	2.184	2.516	2.184	2.516	1.726	1.726	1.910	1.726	1.910	ns
LVC MOS25_S_12	0.988	0.988	1.042	0.988	1.042	2.558	2.558	2.840	2.558	2.840	1.971	1.971	2.194	1.971	2.194	ns
LVC MOS25_S_16	0.988	0.988	1.042	0.988	1.042	2.449	2.449	2.740	2.449	2.740	1.852	1.852	2.063	1.852	2.063	ns
LVC MOS25_S_4	0.988	0.988	1.042	0.988	1.042	2.770	2.770	3.066	2.770	3.066	2.224	2.224	2.458	2.224	2.458	ns
LVC MOS25_S_8	0.988	0.988	1.042	0.988	1.042	2.663	2.663	2.963	2.663	2.963	2.091	2.091	2.373	2.091	2.373	ns
LVC MOS33_F_12	1.154	1.154	1.213	1.154	1.213	2.415	2.415	2.651	2.415	2.651	1.754	1.754	1.915	1.754	1.915	ns
LVC MOS33_F_16	1.154	1.154	1.213	1.154	1.213	2.383	2.383	2.603	2.383	2.603	1.734	1.734	1.869	1.734	1.869	ns
LVC MOS33_F_4	1.154	1.154	1.213	1.154	1.213	2.541	2.541	2.765	2.541	2.765	1.932	1.932	2.135	1.932	2.135	ns
LVC MOS33_F_8	1.154	1.154	1.213	1.154	1.213	2.603	2.603	2.822	2.603	2.822	1.937	1.937	2.130	1.937	2.130	ns
LVC MOS33_S_12	1.154	1.154	1.213	1.154	1.213	2.705	2.705	3.047	2.705	3.047	2.049	2.049	2.318	2.049	2.318	ns
LVC MOS33_S_16	1.154	1.154	1.213	1.154	1.213	2.714	2.714	3.024	2.714	3.024	2.028	2.028	2.232	2.028	2.232	ns
LVC MOS33_S_4	1.154	1.154	1.213	1.154	1.213	2.999	2.999	3.340	2.999	3.340	2.320	2.320	2.610	2.320	2.610	ns

Table 76: IOB High Performance (HP) Switching Characteristics (Cont'd)

I/O Standards	T _{INBUF_DELAY_PAD_I}					T _{OUTBUF_DELAY_O_PAD}					T _{OUTBUF_DELAY_TD_PAD}					Units
	0.90V		0.85V		0.72V	0.90V		0.85V		0.72V	0.90V		0.85V		0.72V	
	-3	-2	-1	-2	-1	-3	-2	-1	-2	-1	-3	-2	-1	-2	-1	
DIFF_SSTL12_F	0.394	0.394	0.402	0.394	0.402	0.412	0.412	0.430	0.412	0.430	0.538	0.538	0.566	0.538	0.566	ns
DIFF_SSTL12_M	0.394	0.394	0.402	0.394	0.402	0.553	0.553	0.584	0.553	0.584	0.641	0.641	0.676	0.641	0.676	ns
DIFF_SSTL12_S	0.394	0.394	0.402	0.394	0.402	0.758	0.758	0.808	0.758	0.808	0.823	0.823	0.879	0.823	0.879	ns
DIFF_SSTL135_DCI_F	0.371	0.371	0.402	0.371	0.402	0.411	0.411	0.428	0.411	0.428	0.537	0.537	0.565	0.537	0.565	ns
DIFF_SSTL135_DCI_M	0.371	0.371	0.402	0.371	0.402	0.551	0.551	0.582	0.551	0.582	0.645	0.645	0.685	0.645	0.685	ns
DIFF_SSTL135_DCI_S	0.371	0.371	0.402	0.371	0.402	0.746	0.746	0.799	0.746	0.799	0.829	0.829	0.893	0.829	0.893	ns
DIFF_SSTL135_F	0.375	0.375	0.402	0.375	0.402	0.408	0.408	0.428	0.408	0.428	0.528	0.528	0.561	0.528	0.561	ns
DIFF_SSTL135_M	0.375	0.375	0.402	0.375	0.402	0.555	0.555	0.585	0.555	0.585	0.641	0.641	0.679	0.641	0.679	ns
DIFF_SSTL135_S	0.375	0.375	0.402	0.375	0.402	0.772	0.772	0.823	0.772	0.823	0.827	0.827	0.878	0.827	0.878	ns
DIFF_SSTL15_DCI_F	0.397	0.397	0.417	0.397	0.417	0.412	0.412	0.429	0.412	0.429	0.531	0.531	0.563	0.531	0.563	ns
DIFF_SSTL15_DCI_M	0.397	0.397	0.417	0.397	0.417	0.553	0.553	0.583	0.553	0.583	0.645	0.645	0.685	0.645	0.685	ns
DIFF_SSTL15_DCI_S	0.397	0.397	0.417	0.397	0.417	0.768	0.768	0.822	0.768	0.822	0.847	0.847	0.912	0.847	0.912	ns
DIFF_SSTL15_F	0.404	0.404	0.417	0.404	0.417	0.424	0.424	0.445	0.424	0.445	0.551	0.551	0.577	0.551	0.577	ns
DIFF_SSTL15_M	0.404	0.404	0.417	0.404	0.417	0.554	0.554	0.585	0.554	0.585	0.639	0.639	0.677	0.639	0.677	ns
DIFF_SSTL15_S	0.404	0.404	0.417	0.404	0.417	0.767	0.767	0.817	0.767	0.817	0.813	0.813	0.867	0.813	0.867	ns
DIFF_SSTL18_I_DCI_F	0.320	0.320	0.336	0.320	0.336	0.445	0.445	0.461	0.445	0.461	0.566	0.566	0.595	0.566	0.595	ns
DIFF_SSTL18_I_DCI_M	0.320	0.320	0.336	0.320	0.336	0.554	0.554	0.585	0.554	0.585	0.644	0.644	0.683	0.644	0.683	ns
DIFF_SSTL18_I_DCI_S	0.320	0.320	0.336	0.320	0.336	0.762	0.762	0.818	0.762	0.818	0.837	0.837	0.899	0.837	0.899	ns
DIFF_SSTL18_I_F	0.316	0.316	0.336	0.316	0.336	0.454	0.454	0.476	0.454	0.476	0.578	0.578	0.608	0.578	0.608	ns
DIFF_SSTL18_I_M	0.316	0.316	0.336	0.316	0.336	0.571	0.571	0.603	0.571	0.603	0.652	0.652	0.692	0.652	0.692	ns
DIFF_SSTL18_I_S	0.316	0.316	0.336	0.316	0.336	0.782	0.782	0.835	0.782	0.835	0.816	0.816	0.870	0.816	0.870	ns
HSLVDCI_15_F	0.393	0.393	0.415	0.393	0.415	0.425	0.425	0.443	0.425	0.443	0.548	0.548	0.579	0.548	0.579	ns
HSLVDCI_15_M	0.393	0.393	0.415	0.393	0.415	0.552	0.552	0.581	0.552	0.581	0.644	0.644	0.684	0.644	0.684	ns
HSLVDCI_15_S	0.393	0.393	0.415	0.393	0.415	0.748	0.748	0.802	0.748	0.802	0.827	0.827	0.890	0.827	0.890	ns
HSLVDCI_18_F	0.424	0.424	0.447	0.424	0.447	0.445	0.445	0.461	0.445	0.461	0.566	0.566	0.595	0.566	0.595	ns
HSLVDCI_18_M	0.424	0.424	0.447	0.424	0.447	0.567	0.567	0.598	0.567	0.598	0.658	0.658	0.699	0.658	0.699	ns
HSLVDCI_18_S	0.424	0.424	0.447	0.424	0.447	0.761	0.761	0.817	0.761	0.817	0.836	0.836	0.900	0.836	0.900	ns
HSTL_I_12_F	0.378	0.378	0.399	0.378	0.399	0.423	0.423	0.443	0.423	0.443	0.553	0.553	0.582	0.553	0.582	ns
HSTL_I_12_M	0.378	0.378	0.399	0.378	0.399	0.551	0.551	0.582	0.551	0.582	0.642	0.642	0.679	0.642	0.679	ns
HSTL_I_12_S	0.378	0.378	0.399	0.378	0.399	0.750	0.750	0.799	0.750	0.799	0.813	0.813	0.868	0.813	0.868	ns
HSTL_I_18_F	0.322	0.322	0.339	0.322	0.339	0.456	0.456	0.474	0.456	0.474	0.576	0.576	0.606	0.576	0.606	ns
HSTL_I_18_M	0.322	0.322	0.339	0.322	0.339	0.569	0.569	0.602	0.569	0.602	0.653	0.653	0.692	0.653	0.692	ns
HSTL_I_18_S	0.322	0.322	0.339	0.322	0.339	0.781	0.781	0.833	0.781	0.833	0.816	0.816	0.871	0.816	0.871	ns
HSTL_I_DCI_12_F	0.378	0.378	0.399	0.378	0.399	0.406	0.406	0.429	0.406	0.429	0.534	0.534	0.564	0.534	0.564	ns
HSTL_I_DCI_12_M	0.378	0.378	0.399	0.378	0.399	0.556	0.556	0.586	0.556	0.586	0.654	0.654	0.694	0.654	0.694	ns
HSTL_I_DCI_12_S	0.378	0.378	0.399	0.378	0.399	0.754	0.754	0.803	0.754	0.803	0.842	0.842	0.907	0.842	0.907	ns
HSTL_I_DCI_18_F	0.321	0.321	0.339	0.321	0.339	0.445	0.445	0.461	0.445	0.461	0.566	0.566	0.595	0.566	0.595	ns
HSTL_I_DCI_18_M	0.321	0.321	0.339	0.321	0.339	0.554	0.554	0.585	0.554	0.585	0.643	0.643	0.684	0.643	0.684	ns
HSTL_I_DCI_18_S	0.321	0.321	0.339	0.321	0.339	0.761	0.761	0.817	0.761	0.817	0.836	0.836	0.900	0.836	0.900	ns
HSTL_I_DCI_F	0.393	0.393	0.415	0.393	0.415	0.431	0.431	0.445	0.431	0.445	0.555	0.555	0.575	0.555	0.575	ns
HSTL_I_DCI_M	0.393	0.393	0.415	0.393	0.415	0.552	0.552	0.581	0.552	0.581	0.644	0.644	0.684	0.644	0.684	ns

Table 76: IOB High Performance (HP) Switching Characteristics (Cont'd)

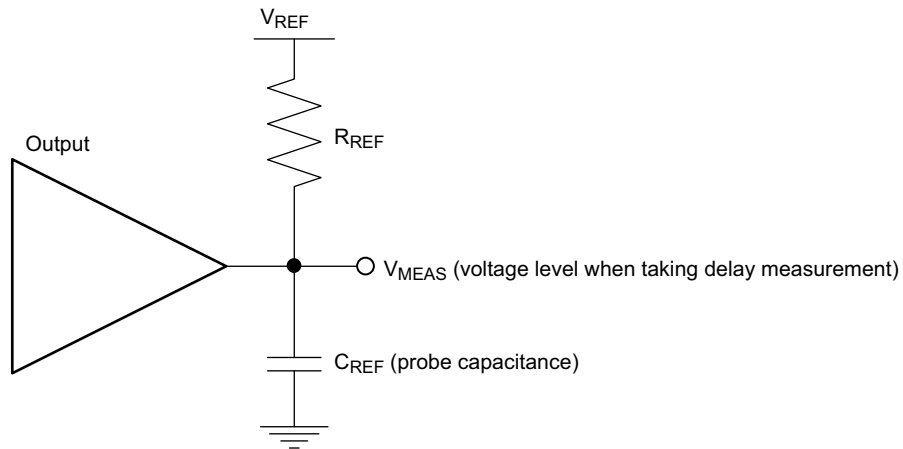
I/O Standards	T _{INBUF_DELAY_PAD_I}					T _{OUTBUF_DELAY_O_PAD}					T _{OUTBUF_DELAY_TD_PAD}					Units
	0.90V		0.85V		0.72V	0.90V		0.85V		0.72V	0.90V		0.85V		0.72V	
	-3	-2	-1	-2	-1	-3	-2	-1	-2	-1	-3	-2	-1	-2	-1	
HSTL_I_DCI_S	0.393	0.393	0.415	0.393	0.415	0.766	0.766	0.821	0.766	0.821	0.847	0.847	0.912	0.847	0.912	ns
HSTL_I_F	0.378	0.378	0.399	0.378	0.399	0.423	0.423	0.443	0.423	0.443	0.549	0.549	0.581	0.549	0.581	ns
HSTL_I_M	0.378	0.378	0.399	0.378	0.399	0.554	0.554	0.585	0.554	0.585	0.640	0.640	0.677	0.640	0.677	ns
HSTL_I_S	0.378	0.378	0.399	0.378	0.399	0.766	0.766	0.816	0.766	0.816	0.811	0.811	0.866	0.811	0.866	ns
HSUL_12_DCI_F	0.378	0.378	0.399	0.378	0.399	0.425	0.425	0.443	0.425	0.443	0.558	0.558	0.586	0.558	0.586	ns
HSUL_12_DCI_M	0.378	0.378	0.399	0.378	0.399	0.556	0.556	0.586	0.556	0.586	0.654	0.654	0.694	0.654	0.694	ns
HSUL_12_DCI_S	0.378	0.378	0.399	0.378	0.399	0.736	0.736	0.784	0.736	0.784	0.821	0.821	0.886	0.821	0.886	ns
HSUL_12_F	0.378	0.378	0.399	0.378	0.399	0.412	0.412	0.430	0.412	0.430	0.538	0.538	0.566	0.538	0.566	ns
HSUL_12_M	0.378	0.378	0.399	0.378	0.399	0.551	0.551	0.582	0.551	0.582	0.642	0.642	0.679	0.642	0.679	ns
HSUL_12_S	0.378	0.378	0.399	0.378	0.399	0.750	0.750	0.799	0.750	0.799	0.813	0.813	0.868	0.813	0.868	ns
LVC MOS12_F_2	0.512	0.512	0.555	0.512	0.555	0.672	0.672	0.692	0.672	0.692	0.898	0.898	0.922	0.898	0.922	ns
LVC MOS12_F_4	0.512	0.512	0.555	0.512	0.555	0.504	0.504	0.521	0.504	0.521	0.664	0.664	0.693	0.664	0.693	ns
LVC MOS12_F_6	0.512	0.512	0.555	0.512	0.555	0.485	0.485	0.507	0.485	0.507	0.634	0.634	0.669	0.634	0.669	ns
LVC MOS12_F_8	0.512	0.512	0.555	0.512	0.555	0.465	0.465	0.489	0.465	0.489	0.611	0.611	0.666	0.611	0.666	ns
LVC MOS12_M_2	0.512	0.512	0.555	0.512	0.555	0.708	0.708	0.727	0.708	0.727	0.916	0.916	0.945	0.916	0.945	ns
LVC MOS12_M_4	0.512	0.512	0.555	0.512	0.555	0.550	0.550	0.573	0.550	0.573	0.664	0.664	0.690	0.664	0.690	ns
LVC MOS12_M_6	0.512	0.512	0.555	0.512	0.555	0.527	0.527	0.554	0.527	0.554	0.622	0.622	0.652	0.622	0.652	ns
LVC MOS12_M_8	0.512	0.512	0.555	0.512	0.555	0.540	0.540	0.571	0.540	0.571	0.614	0.614	0.649	0.614	0.649	ns
LVC MOS12_S_2	0.512	0.512	0.555	0.512	0.555	0.767	0.767	0.803	0.767	0.803	0.990	0.990	1.024	0.990	1.024	ns
LVC MOS12_S_4	0.512	0.512	0.555	0.512	0.555	0.666	0.666	0.704	0.666	0.704	0.803	0.803	0.848	0.803	0.848	ns
LVC MOS12_S_6	0.512	0.512	0.555	0.512	0.555	0.657	0.657	0.695	0.657	0.695	0.732	0.732	0.774	0.732	0.774	ns
LVC MOS12_S_8	0.512	0.512	0.555	0.512	0.555	0.708	0.708	0.761	0.708	0.761	0.745	0.745	0.790	0.745	0.790	ns
LVC MOS15_F_12	0.414	0.414	0.445	0.414	0.445	0.500	0.500	0.522	0.500	0.522	0.647	0.647	0.682	0.647	0.682	ns
LVC MOS15_F_2	0.414	0.414	0.445	0.414	0.445	0.702	0.702	0.722	0.702	0.722	0.919	0.919	0.940	0.919	0.940	ns
LVC MOS15_F_4	0.414	0.414	0.445	0.414	0.445	0.579	0.579	0.601	0.579	0.601	0.755	0.755	0.781	0.755	0.781	ns
LVC MOS15_F_6	0.414	0.414	0.445	0.414	0.445	0.547	0.547	0.569	0.547	0.569	0.711	0.711	0.742	0.711	0.742	ns
LVC MOS15_F_8	0.414	0.414	0.445	0.414	0.445	0.518	0.518	0.538	0.518	0.538	0.686	0.686	0.703	0.686	0.703	ns
LVC MOS15_M_12	0.414	0.414	0.445	0.414	0.445	0.607	0.607	0.644	0.607	0.644	0.637	0.637	0.676	0.637	0.676	ns
LVC MOS15_M_2	0.414	0.414	0.445	0.414	0.445	0.741	0.741	0.770	0.741	0.770	0.938	0.938	0.962	0.938	0.962	ns
LVC MOS15_M_4	0.414	0.414	0.445	0.414	0.445	0.625	0.625	0.651	0.625	0.651	0.754	0.754	0.786	0.754	0.786	ns
LVC MOS15_M_6	0.414	0.414	0.445	0.414	0.445	0.576	0.576	0.604	0.576	0.604	0.674	0.674	0.710	0.674	0.710	ns
LVC MOS15_M_8	0.414	0.414	0.445	0.414	0.445	0.568	0.568	0.601	0.568	0.601	0.639	0.639	0.681	0.639	0.681	ns
LVC MOS15_S_12	0.414	0.414	0.445	0.414	0.445	0.788	0.788	0.855	0.788	0.855	0.695	0.695	0.733	0.695	0.733	ns
LVC MOS15_S_2	0.414	0.414	0.445	0.414	0.445	0.829	0.829	0.864	0.829	0.864	1.039	1.039	1.079	1.039	1.079	ns
LVC MOS15_S_4	0.414	0.414	0.445	0.414	0.445	0.687	0.687	0.725	0.687	0.725	0.813	0.813	0.851	0.813	0.851	ns
LVC MOS15_S_6	0.414	0.414	0.445	0.414	0.445	0.671	0.671	0.710	0.671	0.710	0.726	0.726	0.763	0.726	0.763	ns
LVC MOS15_S_8	0.414	0.414	0.445	0.414	0.445	0.704	0.704	0.755	0.704	0.755	0.721	0.721	0.758	0.721	0.758	ns
LVC MOS18_F_12	0.418	0.418	0.445	0.418	0.445	0.573	0.573	0.601	0.573	0.601	0.731	0.731	0.769	0.731	0.769	ns
LVC MOS18_F_2	0.418	0.418	0.445	0.418	0.445	0.739	0.739	0.760	0.739	0.760	0.945	0.945	0.971	0.945	0.971	ns
LVC MOS18_F_4	0.418	0.418	0.445	0.418	0.445	0.609	0.609	0.630	0.609	0.630	0.778	0.778	0.802	0.778	0.802	ns
LVC MOS18_F_6	0.418	0.418	0.445	0.418	0.445	0.603	0.603	0.633	0.603	0.633	0.781	0.781	0.808	0.781	0.808	ns

Table 76: IOB High Performance (HP) Switching Characteristics (Cont'd)

I/O Standards	T _{INBUF_DELAY_PAD_I}					T _{OUTBUF_DELAY_O_PAD}					T _{OUTBUF_DELAY_TD_PAD}					Units
	0.90V		0.85V		0.72V	0.90V		0.85V		0.72V	0.90V		0.85V		0.72V	
	-3	-2	-1	-2	-1	-3	-2	-1	-2	-1	-3	-2	-1	-2	-1	
LVC MOS18_F_8	0.418	0.418	0.445	0.418	0.445	0.573	0.573	0.600	0.573	0.600	0.733	0.733	0.767	0.733	0.767	ns
LVC MOS18_M_12	0.418	0.418	0.445	0.418	0.445	0.640	0.640	0.678	0.640	0.678	0.670	0.670	0.709	0.670	0.709	ns
LVC MOS18_M_2	0.418	0.418	0.445	0.418	0.445	0.798	0.798	0.822	0.798	0.822	0.991	0.991	1.016	0.991	1.016	ns
LVC MOS18_M_4	0.418	0.418	0.445	0.418	0.445	0.664	0.664	0.693	0.664	0.693	0.798	0.798	0.836	0.798	0.836	ns
LVC MOS18_M_6	0.418	0.418	0.445	0.418	0.445	0.629	0.629	0.663	0.629	0.663	0.735	0.735	0.775	0.735	0.775	ns
LVC MOS18_M_8	0.418	0.418	0.445	0.418	0.445	0.626	0.626	0.661	0.626	0.661	0.705	0.705	0.746	0.705	0.746	ns
LVC MOS18_S_12	0.418	0.418	0.445	0.418	0.445	0.795	0.795	0.861	0.795	0.861	0.683	0.683	0.721	0.683	0.721	ns
LVC MOS18_S_2	0.418	0.418	0.445	0.418	0.445	0.862	0.862	0.897	0.862	0.897	1.076	1.076	1.098	1.076	1.098	ns
LVC MOS18_S_4	0.418	0.418	0.445	0.418	0.445	0.716	0.716	0.758	0.716	0.758	0.829	0.829	0.872	0.829	0.872	ns
LVC MOS18_S_6	0.418	0.418	0.445	0.418	0.445	0.682	0.682	0.724	0.682	0.724	0.724	0.724	0.762	0.724	0.762	ns
LVC MOS18_S_8	0.418	0.418	0.445	0.418	0.445	0.707	0.707	0.760	0.707	0.760	0.709	0.709	0.745	0.709	0.745	ns
LVDCI_15_F	0.425	0.425	0.462	0.425	0.462	0.426	0.426	0.443	0.426	0.443	0.548	0.548	0.581	0.548	0.581	ns
LVDCI_15_M	0.425	0.425	0.462	0.425	0.462	0.553	0.553	0.582	0.553	0.582	0.645	0.645	0.685	0.645	0.685	ns
LVDCI_15_S	0.425	0.425	0.462	0.425	0.462	0.749	0.749	0.803	0.749	0.803	0.821	0.821	0.890	0.821	0.890	ns
LVDCI_18_F	0.414	0.414	0.447	0.414	0.447	0.441	0.441	0.459	0.441	0.459	0.560	0.560	0.589	0.560	0.589	ns
LVDCI_18_M	0.414	0.414	0.447	0.414	0.447	0.554	0.554	0.585	0.554	0.585	0.644	0.644	0.683	0.644	0.683	ns
LVDCI_18_S	0.414	0.414	0.447	0.414	0.447	0.760	0.760	0.818	0.760	0.818	0.837	0.837	0.899	0.837	0.899	ns
LVDS	0.539	0.539	0.620	0.539	0.620	0.626	0.626	0.662	0.626	0.662	960.447	960.447	960.447	960.447	960.447	ns
MIPI_DPHY_DCI_HS	0.386	0.386	0.415	0.386	0.415	0.502	0.502	0.522	0.502	0.522	N/A	N/A	N/A	N/A	N/A	ns
MIPI_DPHY_DCI_LP	8.438	8.438	8.792	8.438	8.792	0.914	0.914	0.937	0.914	0.937	N/A	N/A	N/A	N/A	N/A	ns
POD10_DCI_F	0.408	0.408	0.430	0.408	0.430	0.425	0.425	0.444	0.425	0.444	0.555	0.555	0.584	0.555	0.584	ns
POD10_DCI_M	0.408	0.408	0.430	0.408	0.430	0.542	0.542	0.571	0.542	0.571	0.640	0.640	0.681	0.640	0.681	ns
POD10_DCI_S	0.408	0.408	0.430	0.408	0.430	0.754	0.754	0.815	0.754	0.815	0.850	0.850	0.917	0.850	0.917	ns
POD10_F	0.407	0.407	0.430	0.407	0.430	0.438	0.438	0.459	0.438	0.459	0.569	0.569	0.601	0.569	0.601	ns
POD10_M	0.407	0.407	0.430	0.407	0.430	0.538	0.538	0.568	0.538	0.568	0.630	0.630	0.667	0.630	0.667	ns
POD10_S	0.407	0.407	0.430	0.407	0.430	0.766	0.766	0.821	0.766	0.821	0.836	0.836	0.894	0.836	0.894	ns
POD12_DCI_F	0.409	0.409	0.431	0.409	0.431	0.425	0.425	0.443	0.425	0.443	0.558	0.558	0.586	0.558	0.586	ns
POD12_DCI_M	0.409	0.409	0.431	0.409	0.431	0.543	0.543	0.572	0.543	0.572	0.638	0.638	0.678	0.638	0.678	ns
POD12_DCI_S	0.409	0.409	0.431	0.409	0.431	0.772	0.772	0.822	0.772	0.822	0.862	0.862	0.929	0.862	0.929	ns
POD12_F	0.409	0.409	0.431	0.409	0.431	0.455	0.455	0.476	0.455	0.476	0.595	0.595	0.626	0.595	0.626	ns
POD12_M	0.409	0.409	0.431	0.409	0.431	0.551	0.551	0.582	0.551	0.582	0.641	0.641	0.679	0.641	0.679	ns
POD12_S	0.409	0.409	0.431	0.409	0.431	0.767	0.767	0.817	0.767	0.817	0.832	0.832	0.889	0.832	0.889	ns
SLVS_400_18	0.539	0.539	0.620	0.539	0.620	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	ns
SSTL12_DCI_F	0.381	0.381	0.399	0.381	0.399	0.425	0.425	0.443	0.425	0.443	0.558	0.558	0.586	0.558	0.586	ns
SSTL12_DCI_M	0.381	0.381	0.399	0.381	0.399	0.557	0.557	0.587	0.557	0.587	0.654	0.654	0.694	0.654	0.694	ns
SSTL12_DCI_S	0.381	0.381	0.399	0.381	0.399	0.754	0.754	0.803	0.754	0.803	0.842	0.842	0.908	0.842	0.908	ns
SSTL12_F	0.403	0.403	0.403	0.403	0.403	0.412	0.412	0.430	0.412	0.430	0.538	0.538	0.566	0.538	0.566	ns
SSTL12_M	0.403	0.403	0.403	0.403	0.403	0.553	0.553	0.584	0.553	0.584	0.641	0.641	0.676	0.641	0.676	ns
SSTL12_S	0.403	0.403	0.403	0.403	0.403	0.758	0.758	0.808	0.758	0.808	0.823	0.823	0.879	0.823	0.879	ns
SSTL135_DCI_F	0.366	0.366	0.399	0.366	0.399	0.411	0.411	0.428	0.411	0.428	0.537	0.537	0.565	0.537	0.565	ns
SSTL135_DCI_M	0.366	0.366	0.399	0.366	0.399	0.551	0.551	0.582	0.551	0.582	0.645	0.645	0.685	0.645	0.685	ns

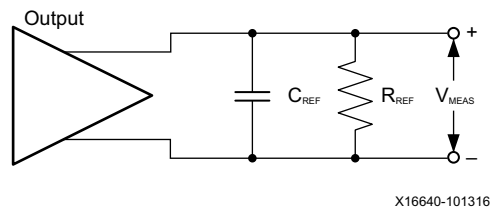
Output Delay Measurement Methodology

Output delays are measured with short output traces. Standard termination was used for all testing. The propagation delay of the trace is characterized separately and subtracted from the final measurement, and is therefore not included in the generalized test setups shown in [Figure 1](#) and [Figure 2](#).



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Figure 1: Single-Ended Test Setup



X16640-101316

Figure 2: Differential Test Setup

Parameters V_{REF} , R_{REF} , C_{REF} , and V_{MEAS} fully describe the test conditions for each I/O standard. The most accurate prediction of propagation delay in any given application can be obtained through IBIS simulation, using this method:

1. Simulate the output driver of choice into the generalized test setup using values from [Table 79](#).
2. Record the time to V_{MEAS} .
3. Simulate the output driver of choice into the actual PCB trace and load using the appropriate IBIS model or capacitance value to represent the load.
4. Record the time to V_{MEAS} .
5. Compare the results of [step 2](#) and [step 4](#). The increase or decrease in delay yields the actual propagation delay of the PCB trace.

Table 79: Output Delay Measurement Methodology

Description	I/O Standard Attribute	R _{REF} (Ω)	C _{REF} ⁽¹⁾ (pF)	V _{MEAS} (V)	V _{REF} (V)
LVC MOS, 1.2V	LVC MOS12	1M	0	0.6	0
LVC MOS, 1.5V	LVC MOS15	1M	0	0.75	0
LVC MOS, 1.8V	LVC MOS18	1M	0	0.9	0
LVC MOS, 2.5V	LVC MOS25	1M	0	1.25	0
LVC MOS, 3.3V	LVC MOS33	1M	0	1.65	0
LVTTL, 3.3V	LVTTL	1M	0	1.65	0
LVDCI, HSLVDCI, 1.5V	LVDCI_15, HSLVDCI_15	50	0	V _{REF}	0.75
LVDCI, HSLVDCI, 1.8V	LVDCI_15, HSLVDCI_18	50	0	V _{REF}	0.9
HSTL (high-speed transceiver logic), class I, 1.2V	HSTL_I_12	50	0	V _{REF}	0.6
HSTL, class I, 1.5V	HSTL_I	50	0	V _{REF}	0.75
HSTL, class I, 1.8V	HSTL_I_18	50	0	V _{REF}	0.9
HSUL (high-speed unterminated logic), 1.2V	HSUL_12	50	0	V _{REF}	0.6
SSTL12 (stub series terminated logic), 1.2V	SSTL12	50	0	V _{REF}	0.6
SSTL135 and SSTL135 class II, 1.35V	SSTL135, SSTL135_II	50	0	V _{REF}	0.675
SSTL15 and SSTL15 class II, 1.5V	SSTL15, SSTL15_II	50	0	V _{REF}	0.75
SSTL18, class I and class II, 1.8V	SSTL18_I, SSTL18_II	50	0	V _{REF}	0.9
POD10, 1.0V	POD10	50	0	V _{REF}	1.0
POD12, 1.2V	POD12	50	0	V _{REF}	1.2
DIFF_HSTL, class I, 1.2V	DIFF_HSTL_I_12	50	0	V _{REF}	0.6
DIFF_HSTL, class I, 1.5V	DIFF_HSTL_I	50	0	V _{REF}	0.75
DIFF_HSTL, class I, 1.8V	DIFF_HSTL_I_18	50	0	V _{REF}	0.9
DIFF_HSUL, 1.2V	DIFF_HSUL_12	50	0	V _{REF}	0.6
DIFF_SSTL12, 1.2V	DIFF_SSTL12	50	0	V _{REF}	0.6
DIFF_SSTL135 and DIFF_SSTL135 class II, 1.35V	DIFF_SSTL135, DIFF_SSTL135_II	50	0	V _{REF}	0.675
DIFF_SSTL15 and DIFF_SSTL15 class II, 1.5V	DIFF_SSTL15, DIFF_SSTL15_II	50	0	V _{REF}	0.75
DIFF_SSTL18, class I and II, 1.8V	DIFF_SSTL18_I, DIFF_SSTL18_II	50	0	V _{REF}	0.9
DIFF_POD10, 1.0V	DIFF_POD10	50	0	V _{REF}	1.0
DIFF_POD12, 1.2V	DIFF_POD12	50	0	V _{REF}	1.2
LVDS (low-voltage differential signaling), 1.8V	LVDS	100	0	0 ⁽²⁾	0
SUB_LVDS, 1.8V	SUB_LVDS	100	0	0 ⁽²⁾	0
MIPI D-PHY (high speed) 1.2V	MIPI_DPHY_DCI_HS	100	0	0 ⁽²⁾	0
MIPI D-PHY (low power) 1.2V	MIPI_DPHY_DCI_LP	1M	0	0.6	0

Notes:

1. C_{REF} is the capacitance of the probe, nominally 0 pF.
2. The value given is the differential output voltage.

Package Parameter Guidelines

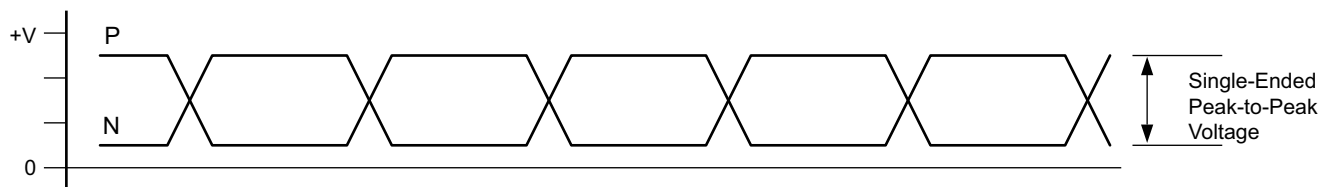
The parameters in this section provide the necessary values for calculating timing budgets for clock transmitter and receiver data-valid windows.

Table 93: Package Skew

Symbol	Description	Device	Package	Value	Units
PKGSKEW	Package Skew	XCZU2	SBVA484	105	ps
			SFVA625	108	ps
			SFVC784	93	ps
		XCZU3	SBVA484	105	ps
			SFVA625	108	ps
			SFVC784	93	ps
		XCZU4	SFVC784		ps
			FBVB900		ps
		XCZU5	SFVC784		ps
			FBVB900		ps
		XCZU6	FFVC900	119	ps
			FFVB1156	134	ps
		XCZU7	FBVB900	141	ps
			FFVC1156	175	ps
			FFVF1517	305	ps
		XCZU9	FFVC900	119	ps
			FFVB1156	134	ps
		XCZU11	FFVC1156		ps
			FFVB1517		ps
			FFVF1517		ps
			FFVC1760	215	ps
		XCZU15	FFVC900	118	ps
			FFVB1156	132	ps
		XCZU17	FFVB1517	221	ps
FFVC1760	226		ps		
FFVD1760	178		ps		
FFVE1924	174		ps		
XCZU19	FFVB1517	221	ps		
	FFVC1760	226	ps		
	FFVD1760	178	ps		
	FFVE1924	174	ps		

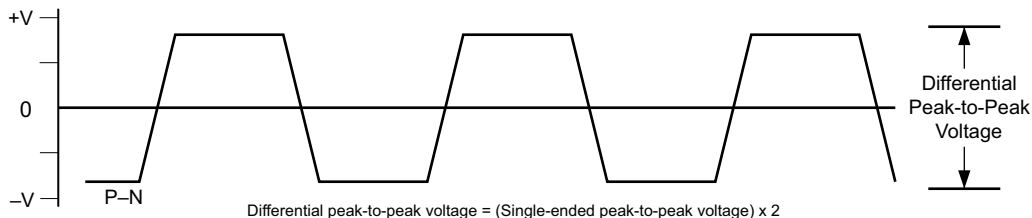
Notes:

1. These values represent the worst-case skew between any two SelectIO resources in the package: shortest delay to longest delay from die pad to ball.
2. Package delay information is available for these device/package combinations. This information can be used to deskew the package.



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Figure 3: Single-Ended Peak-to-Peak Voltage



X16639-101316

Figure 4: Differential Peak-to-Peak Voltage

Table 95 and Table 96 summarize the DC specifications of the GTH transceivers input and output clocks in Zynq UltraScale+ MPSoC. Consult the *UltraScale Architecture GTH Transceiver User Guide (UG576)* for further details.

Table 95: GTH Transceiver Clock Input Level Specification

Symbol	DC Parameter	Min	Typ	Max	Units
V_{IDIFF}	Differential peak-to-peak input voltage.	250	–	2000	mV
R_{IN}	Differential input resistance.	–	100	–	Ω
C_{EXT}	Required external AC coupling capacitor.	–	10	–	nF

Table 96: GTH Transceiver Clock Output Level Specification

Symbol	Description	Conditions	Min	Typ	Max	Units
V_{OL}	Output Low voltage for P and N.	$R_T = 100\Omega$ across P and N signals	100	–	330	mV
V_{OH}	Output High voltage for P and N.	$R_T = 100\Omega$ across P and N signals	500	–	700	mV
V_{DDOUT}	Differential output voltage. (P–N), P = High (N–P), N = High	$R_T = 100\Omega$ across P and N signals	300	–	430	mV
V_{CMOUT}	Common mode voltage.	$R_T = 100\Omega$ across P and N signals	300	–	500	mV

GTY Transceiver Switching Characteristics

Consult the *UltraScale Architecture GTY Transceiver User Guide (UG578)* for further information.

Table 109: GTY Transceiver Performance

Symbol	Description	Output Divider	Speed Grade and V _{CCINT} Operating Voltages										Units
			0.90V		0.85V		0.72V		0.72V		0.72V		
			-3	-2	-1	-2	-1	-2	-1	-2	-1	-2	
F _{GTymax}	GTY maximum line rate		32.75		28.21		25.7813		28.21		12.5		Gb/s
F _{GTymin}	GTY minimum line rate		0.5		0.5		0.5		0.5		0.5		Gb/s
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
F _{GTyCRANGE}	CPLL line rate range ⁽¹⁾	1	4.0	12.5	4.0	12.5	4.0	8.5	4.0	12.5	4.0	8.5	Gb/s
		2	2.0	6.25	2.0	6.25	2.0	4.25	2.0	6.25	2.0	4.25	Gb/s
		4	1.0	3.125	1.0	3.125	1.0	2.125	1.0	3.125	1.0	2.125	Gb/s
		8	0.5	1.5625	0.5	1.5625	0.5	1.0625	0.5	1.5625	0.5	1.0625	Gb/s
		16	N/A										Gb/s
		32	N/A										Gb/s
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
F _{GTyQRANGE1}	QPLL0 line rate range ⁽²⁾	1	19.6	32.75	19.6	28.21	19.6	25.7813	19.6	28.21	N/A		Gb/s
		1	9.8	16.375	9.8	16.375	9.8	12.5	9.8	16.375	9.8	12.5	Gb/s
		2	4.9	8.1875	4.9	8.1875	4.9	8.1875	4.9	8.1875	4.9	8.1875	Gb/s
		4	2.45	4.0938	2.45	4.0938	2.45	4.0938	2.45	4.0938	2.45	4.0938	Gb/s
		8	1.225	2.0469	1.225	2.0469	1.225	2.0469	1.225	2.0469	1.225	2.0469	Gb/s
		16	0.6125	1.0234	0.6125	1.0234	0.6125	1.0234	0.6125	1.0234	0.6125	1.0234	Gb/s
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
F _{GTyQRANGE2}	QPLL1 line rate range ⁽³⁾	1	16.0	26.0	16.0	26.0	19.6	25.7813	16.0	26.0	N/A		Gb/s
		1	8.0	13.0	8.0	13.0	8.0	12.5	8.0	13.0	8.0	12.5	Gb/s
		2	4.0	6.5	4.0	6.5	4.0	6.5	4.0	6.5	4.0	6.5	Gb/s
		4	2.0	3.25	2.0	3.25	2.0	3.25	2.0	3.25	2.0	3.25	Gb/s
		8	1.0	1.625	1.0	1.625	1.0	1.625	1.0	1.625	1.0	1.625	Gb/s
		16	0.5	0.8125	0.5	0.8125	0.5	0.8125	0.5	0.8125	0.5	0.8125	Gb/s
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
F _{CPLL} RANGE	CPLL frequency range		2.0	6.25	2.0	6.25	2.0	4.25	2.0	6.25	2.0	4.25	GHz
F _{QPLL0} RANGE	QPLL0 frequency range		9.8	16.375	9.8	16.375	9.8	16.375	9.8	16.375	9.8	16.375	GHz
F _{QPLL1} RANGE	QPLL1 frequency range		8.0	13.0	8.0	13.0	8.0	13.0	8.0	13.0	8.0	13.0	GHz

Notes:

1. The values listed are the rounded results of the calculated equation (2 x CPLL_Frequency)/Output_Divider.
2. The values listed are the rounded results of the calculated equation (2 x QPLL0_Frequency)/Output_Divider.
3. The values listed are the rounded results of the calculated equation (2 x QPLL1_Frequency)/Output_Divider.

GTY Transceiver Electrical Compliance

The *UltraScale Architecture GTY Transceiver User Guide* ([UG578](#)) contains recommended use modes that ensure compliance for the protocols listed in [Table 117](#). The transceiver wizard provides the recommended settings for those use cases and for protocol specific characteristics.

Table 117: GTY Transceiver Protocol List

Protocol	Specification	Serial Rate (Gb/s)	Electrical Compliance
CAUI-4	IEEE 802.3-2012	25.78125	Compliant
28 Gb/s backplane	CEI-25G-LR	25–28.05	Compliant
Interlaken	OIF-CEI-6G, OIF-CEI-11GSR, OIF-CEI-28G-MR	4.25–25.78125	Compliant
100GBASE-KR4	IEEE 802.3bj-2014, CEI-25G-LR	25.78125	Compliant ⁽¹⁾
100GBASE-CR4	IEEE 802.3bj-2014, CEI-25G-LR	25.78125	Compliant ⁽¹⁾
50GBASE-KR4	IEEE 802.3by-2014, CEI-25G-LR	25.78125	Compliant ⁽¹⁾
50GBASE-CR4	IEEE 802.3by-2014, CEI-25G-LR	25.78125	Compliant ⁽¹⁾
25GBASE-KR4	IEEE 802.3by-2014, CEI-25G-LR	25.78125	Compliant ⁽¹⁾
25GBASE-CR4	IEEE 802.3by-2014, CEI-25G-LR	25.78125	Compliant ⁽¹⁾
OTU4 (OTL4.4) CFP2	OIF-CEI-28G-VSR	27.952493–32.75	Compliant
OTU4 (OTL4.4) CFP	OIF-CEI-11G-MR	11.18–13.1	Compliant
CAUI-10	IEEE 802.3-2012	10.3125	Compliant
nPPI	IEEE 802.3-2012	10.3125	Compliant
10GBASE-KR ⁽²⁾	IEEE 802.3-2012	10.3125	Compliant
SFP+	SFF-8431 (SR and LR)	9.95328–11.10	Compliant
XFP	INF-8077i, revision 4.5	10.3125	Compliant
RXAUI	CEI-6G-SR	6.25	Compliant
XAUI	IEEE 802.3-2012	3.125	Compliant
1000BASE-X	IEEE 802.3-2012	1.25	Compliant
5.0G Ethernet	IEEE 802.3bx (PAR)	5	Compliant
2.5G Ethernet	IEEE 802.3bx (PAR)	2.5	Compliant
HiGig, HiGig+, HiGig2	IEEE 802.3-2012	3.74, 6.6	Compliant
QSGMII	QSGMII v1.2 (Cisco System, ENG-46158)	5	Compliant
OTU2	ITU G.8251	10.709225	Compliant
OTU4 (OTL4.10)	OIF-CEI-11G-SR	11.180997	Compliant
OC-3/12/48/192	GR-253-CORE	0.1555–9.956	Compliant
PCIe Gen1, 2, 3	PCI Express base 3.0	2.5, 5.0, and 8.0	Compliant
SDI ⁽³⁾	SMPTE 424M-2006	0.27–2.97	Compliant
UHD-SDI ⁽³⁾	SMPTE ST-2081 6G, SMPTE ST-2082 12G	6 and 12	Compliant
Hybrid memory cube (HMC)	HMC-15G-SR	10, 12.5, and 15.0	Compliant
MoSys bandwidth engine	CEI-11-SR and CEI-11-SR (overclocked)	10.3125, 15.5	Compliant
CPRI	CPRI_v_6_1_2014-07-01	0.6144–12.165	Compliant
Passive optical network (PON)	10G-EPON, 1G-EPON, NG-PON2, XG-PON, and 2.5G-PON	0.155–10.3125	Compliant
JESD204a/b	OIF-CEI-6G, OIF-CEI-11G	3.125–12.5	Compliant

Integrated Interface Block for Interlaken

More information and documentation on solutions using the integrated interface block for Interlaken can be found at [UltraScale+ Interlaken](#). The *UltraScale Architecture and Product Overview (DS890)* lists how many blocks are in each Zynq UltraScale+ MPSoC. This section describes the following Interlaken configurations.

- 12 x 12.5 Gb/s protocol and lane logic mode ([Table 118](#)).
- 6 x 25.78125 Gb/s and 6 x 28.21 Gb/s protocol and lane logic mode ([Table 119](#)).
- 12 x 25.78125 Gb/s lane logic only mode ([Table 120](#)).

Zynq UltraScale+ MPSoCs in the SFVB784, FFVA676, and FFVA1156 packages are only supported using the 12 x 12.5 Gb/s Interlaken configuration. See [Table 109](#) for the F_{GTYMAX} description.

Table 118: Maximum Performance for Interlaken 12 x 12.5 Gb/s Protocol and Lane Logic Mode Designs

Symbol	Description	Speed Grade and V_{CCINT} Operating Voltages										Units
		0.90V		0.85V				0.72V				
		-3	-2	-1	-2	-1	-2	-1				
$F_{RX_SERDES_CLK}$	Receive serializer/deserializer clock	195.32		195.32				195.32				MHz
$F_{TX_SERDES_CLK}$	Transmit serializer/deserializer clock	195.32		195.32				195.32				MHz
F_{DRP_CLK}	Dynamic reconfiguration port clock	250.00		250.00				250.00				MHz
		Min ⁽¹⁾	Max	Min ⁽¹⁾	Max	Min ⁽¹⁾	Max	Min ⁽¹⁾	Max	Min ⁽¹⁾	Max	
F_{CORE_CLK}	Interlaken core clock	300.00	322.27	300.00	322.27	300.00	322.27	300.00	322.27	300.00	322.27	MHz
F_{LBUS_CLK}	Interlaken local bus clock	300.00	322.27	300.00	322.27	300.00	322.27	300.00	322.27	300.00	322.27	MHz

Notes:

1. These are the minimum clock frequencies at the maximum lane performance.

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
04/20/2017	1.3	<p>Updated Table 25, Table 26, and Table 27 to production release for the following devices/speed/temperature grades in Vivado Design Suite 2017.1.</p> <p>XCZU2CG and XCZU2EG: -2E, -2I, -1E, -1I XCZU3CG and XCZU3EG: -2E, -2I, -1E, -1I XCZU6CG and XCZU6EG: -2E, -2I, -1E, -1I XCZU9CG and XCZU9EG: -2E, -2I, -1E, -1I</p> <p>Added -2E ($V_{CCINT} = 0.85V$) speed grade where applicable. Removed -3E speed grade from the XCZU2 and XCZU3 devices in Table 26 and where applicable.</p> <p>In Table 1, updated values and Note 2. In Table 2, added or updated many of the notes. Updated Table 4 including the notes and added Note 6. Moved and updated Table 5. Added Table 8. Updated Table 9 and added Note 4. Updated Table 10 and added Note 1.</p> <p>Revised V_{ICM} in Table 23. Updated Table 30 and removed Note 1. Added Table 31 and Table 32. Updated Table 33 and removed F_{FTMCLK}. Updated $T_{REFPSCLK}$ in Table 34. Updated Note 1 in Table 37. Updated Table 39. Removed the <i>PS NAND Memory Controller Interface</i> section. Significant changes to Table 41 and removed Note 3. Significant changes to Table 42 and updated Note 1. Removed $F_{TSU_REF_CLK}$ from Table 44. Revised Table 45 and added Note 2 and Note 3. Revised Table 46 and added Note 2 and Note 3. Updated Table 48. Updated Table 51 and removed Note 2. Revised Table 52. Revised many of the tables in the <i>PS-GTR Transceiver</i> section. Revised Table 70 and Table 71. Removed Note 8 from Table 74.</p> <p>Updated the values in Table 75, Table 76, Table 77, Table 80, Table 87, Table 88, Table 89, Table 90, and Table 91 to the Vivado Design Suite 2017.1 speed specifications.</p> <p>Updated the values in Table 81 and Table 82. Added values to Table 92. Updated Table 93. Revised D_{VPP_OUT} in Table 94. Update the values in Table 96. Added Note 6 to Table 102. Updated Table 103 and Table 104. Revised D_{VPP_OUT} in Table 106. Updated the values in Table 108. In Table 109 updated the -1 (0.85V) specifications and removed Note 1. In Table 114 updated the -1 (0.85V) specifications and added Note 6. In Table 115 and Table 116, added the 28.21 jitter tolerance values and revised the notes. Revised the <i>Integrated Interface Block for Interlaken</i> and <i>Integrated Interface Block for 100G Ethernet MAC and PCS</i> sections. Revised the <i>Configuration Switching Characteristics</i> section. Removed the <i>eFUSE Programming Conditions</i> table and added the specifications to Table 2 and Table 3.</p>

Date	Version	Description of Revisions
02/10/2017	1.2	<p>Updated some of the maximum voltages in the Processor System (PS) section and other specifications in the Programmable Logic (PL) and GTH or GTY Transceiver sections of Table 1. Updated Table 2, Table 4, Table 6, Table 7, and Table 9. Revised the Power Supply Sequencing section including Table 10. Added PS and VCU ramp times to Table 11. Revised V_{ODIFF} in Table 24. Updated Table 25. Added Note 1 to Table 26. Table 30 replaces the previous three PS memory performance tables. Added values to Table 34, Table 37, and Table 38. Deleted the waveforms in the PS Switching Characteristics section (Figures 1-16 and Figures 25-26). Revised values in the <i>PS NAND Memory Controller Interface</i> section. Added and updated data in Table 40. Added Note 3 to Table 41. Added Note 3 to Table 42. Added Note 1 to Table 45. Updated Table 48 and removed Note 3. Added data to Table 56. Updated Table 60. Added Table 61. Updated Table 63. Revised Table 69. Added data to Table 70. Added Note 2 to Table 71. Updated Table 74 and added Note 4. Updated V_L and V_H values in Table 78. Added T_{MINPER_CLK}, revised F_{REFCLK}, and Note 1 to Table 82. Added $MMCM_FDPRCLK_MAX$ to Table 85 and $PLL_FDPRCLK_MAX$ to Table 86. Added data to Table 94, Table 96, Table 98, Table 101, and updated the note references in Table 102. Updated Table 103 and added Note 8. Updated Table 104 and added Note 7. Added more protocols, Note 1 and Note 2 to Table 105. Removed the <i>GTH Transceiver Protocol Jitter Characteristics</i> section because it is covered in Table 105. Added Note 1 to Table 109. Added data to Table 106, Table 108, Table 110, Table 113. Added Note 2 to Table 112. Added note references in Table 114. Updated Table 115 and added Note 8. Updated Table 116 and added Note 7. Added more protocols and Note 3 to Table 117. Removed the <i>GTY Transceiver Protocol Jitter Characteristics</i> section because it is covered in Table 117. Revised Table 124. Added T_{POR} and updated F_{ICAPCK} in Table 127. Updated the Automotive Applications Disclaimer.</p>
06/20/2016	1.1	<p>Updated the Summary description. In Table 1, revised V_{IN} for HP I/O banks and added clarifications to some descriptions and symbols. Added I_{RPU}, I_{RPD}, and Note 4 to Table 2 and updated $V_{PS_MGTRAVCC}$, the PL System Monitor section, and Note 3 and Note 5. Updated Note 5 in Table 4. Updated the PS Power-On/Off Power Supply Sequencing section including all the voltage supply names. Added $MIPI_DPHY_DCI$ to Table 14, Table 15, and Table 17. Updated Table 23, including removing the V_{CCO} specification and adding Note 1. Added Note 1 to Table 24. Updated Table 25 speed specifications for Vivado Design Suite 2016.1. Added values to Table 28. Updated the -2 value in Table 29. Added $F_{DPLIVEVIDEO}$ and updated $F_{FCIDMACLK}$ in Table 33. Added VCO frequencies to Table 36. Added the T_{PSPOR} minimum to Table 37 and updated Note 1. Added Table 38. Added value delineation over V_{CCINT} operating voltages in Table 39. Revised values for F_{TCK} and T_{TAPTCK}/T_{TCKTAP} in Table 40 and added value delineation over V_{CCINT} operating voltages. Updated the <i>PS NAND Memory Controller Interface</i> section. Revised some units and Note 1 in Table 41 and Table 42. Removed Figure 6: Quad-SPI Interface (Feedback Clock Disabled) Timing. Updated Note 1 of Table 43. Added $F_{TSI_REF_CLK}$ to Table 44 and updated Note 1. In Table 45, revised $T_{DCSDHCLK1}$, $T_{DCSDHCLK2}$, and $T_{DCSDHCLK3}$ and Note 1. In Table 46, revised Note 1. In Table 47, revised Note 1. Revised Table 48, including Note 1, and added Note 2 and Note 3. In Table 49, Table 50, Table 51, and Table 53, revised Note 1. Updated Table 71. Replaced Table 74. Updated Table 75 and Table 76. Updated Table 78 and Table 79. In Table 80, added the Block RAM and FIFO Clock-to-Out Delays section. Updated the R_{IN} and C_{EXT} values in Table 57 and Table 95. Updated the -2 (0.72V) and -1 (0.72V) values and added Note 1 to Table 97. Added Table 100 and Table 112. Added Note 2 to Table 106. Revised data in Table 109. Revised Table 114. Revised data and added notes in the Integrated Interface Block for Interlaken section and Table 121. Moved Table 123. Revised INL in Table 124. Added notes to Table 125 and Table 126. In the <i>eFUSE and Programming Conditions</i> table, updated the I_{PSFS} description.</p>
11/24/2015	1.0	Initial Xilinx release.